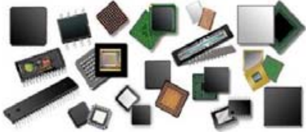

Package Configurations

FORCE TECHNOLOGIES can facilitate the assembly of a wide range of package types and sizes; from 8-pin DIPs to 559-pin PGAs and most types in between.

Ceramic Packages

- **Ceramic SOIC** — Small Outline Integrated Circuit
- **CERDIP** — Ceramic Dual Inline Package with lead frame Windowed or Non-Windowed
- **CERPAC** — Ceramic Package with unformed leads on two opposite sides
- **CERQUAD** — Ceramic Package with unformed leads on all four sides
    - Windowed or Non-Windowed
- **CQFP** — Ceramic Quad Flat Pack with bottom leads on all four sides
- **FLATPACK** — Ceramic Package with bottom leads on two opposite sides
- **JLCC** — Leaded Chip Carrier with "J" bend leads
- **LCC** — Leadless Chip Carrier
- **PGA** — Pin Grid Array
    - Cavity Up or Down
    - With or Without Heat sinks
- **SIDEBRAZE** — Ceramic Dual Inline Package with attached leads
- **MODULES**
    - Ceramic
    - Polyimide-Alum
    - PCB based

Specialty Packages

- **COB** — Chip On Board
- **FLEX CABLE** — Package with integrated cable
- **HYBRID** — Mixed components in same package
- **METAL** or **TO CANS** — Metal Transistor Outline Can-type package
- **MULTICHIP MODULE** — Multiple Integrated Circuits in same package

Plastic Encapsulated Packages

- **PDIP** - .300″ .400″ .600″
- **FLAT PACK/TQFP/PQFP**
- **PLCC**
- **SOIC/SSOP**
- **SOJ**
- **BGA**

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